

Title (en)

THERMAL PRINTING HEAD, SUBSTRATE USED THEREFOR AND METHOD FOR PRODUCING THE SUBSTRATE

Title (de)

THERMODRUCKKOPF, DAFÜR VERWENDETES SUBSTRAT UND VERFAHREN ZUM HERSTELLEN DIESES SUBSTRATS

Title (fr)

TETE D'IMPRIMANTE THERMIQUE, SON SUBSTRAT ET PROCEDE DE FABRICATION DUDIT SUBSTRAT

Publication

EP 0763431 B1 19991027 (EN)

Application

EP 95919630 A 19950524

Priority

- JP 11900394 A 19940531
- JP 17923794 A 19940729
- JP 20184594 A 19940826
- JP 7016295 A 19950328
- JP 7016395 A 19950328
- JP 9500999 W 19950524

Abstract (en)

[origin: EP0763431A1] A thermal printing head which comprises a substrate (2) having a substantially flat surface and made of an insulating material, a heat generating resistor (3) formed on the substrate (2) for forming a plurality of heat generating dots, patterns of conductive material (5, 6) formed on the substrate (2) in such a manner as to be electrically connected to the heat generating resistor (3) and a driving element mounted on the substrate (2) for selectively activating the heat generating dots for generating heat via the patterns of conductive material (5, 6), wherein the substrate (2) has in its thicker portion a hollow portion (10) extending along the heat generating resistor (3). The present invention also provides a method for producing the substrate (2). <IMAGE>

IPC 1-7

B41J 2/335

IPC 8 full level

B41J 2/335 (2006.01); **H05K 1/02** (2006.01); **H05K 1/16** (2006.01)

CPC (source: EP KR US)

B41J 2/335 (2013.01 - KR); **B41J 2/33535** (2013.01 - EP US); **B41J 2/3355** (2013.01 - EP US); **B41J 2/3357** (2013.01 - EP US); **B41J 2/33585** (2013.01 - EP US); **H01L 2224/05554** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/49175** (2013.01 - EP US); **H01L 2224/49431** (2013.01 - EP US); **H01L 2224/49433** (2013.01 - EP US); **H05K 1/0201** (2013.01 - EP US); **H05K 1/16** (2013.01 - EP US)

Citation (examination)

EP 0535557 A1 19930407 - ROHM CO LTD [JP]

Cited by

CN102126353A; EP1780020A3; EP2172342A1; EP1384590A1; US7522178B2; US8169452B2; US6784910B2

Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

EP 0763431 A1 19970319; **EP 0763431 A4 19970326**; **EP 0763431 B1 19991027**; CN 1086639 C 20020626; CN 1149855 A 19970514; DE 69513021 D1 19991202; DE 69513021 T2 20001012; KR 100225259 B1 19991015; KR 970703244 A 19970703; TW 468783 U 20011211; US 5940109 A 19990817; WO 9532866 A1 19951207

DOCDB simple family (application)

EP 95919630 A 19950524; CN 95193355 A 19950524; DE 69513021 T 19950524; JP 9500999 W 19950524; KR 19960706790 A 19961129; TW 86205647 U 19950526; US 96124797 A 19971030